



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 4981
Hiroshi TAKANASHI et al. : Docket No. 2000-1749
Serial No. 09/739,750 : Group Art Unit 1752
Filed December 20, 2000 : Examiner S. Lee

6/B

NEGATIVE-WORKING PHOTSENSITIVE :
RESIN COMPOSITION AND
PHOTSENSITIVE RESIN PLATE USING :
THE SAME

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEE FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975.

SUPPLEMENTAL RESPONSE

RECEIVED

Assistant Commissioner for Patents,
Washington, D.C.

APR 4 2002

TC 1700

Sir:

Further to the response filed on March 7, 2002, please amend the present application as follows:

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Twice Amended) A negative-working photosensitive composition comprising:
- (A) a film-forming polymer
 - (B) an unsaturated compound having a radical polymerizable ethylenic double bond,
 - (C) a photopolymerization initiator,
 - (D) a thermal polymerization inhibitor, and
 - (E) at least one member selected from compounds represented by the following

formula:

B1